

Material Composition Data

Product: GTXO-566

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Golledge

Timing Is Everything

GTXO-566 - 3V & 5V SM (VC)TCXO Clipped Sine

GTXO-566 - 3V & 5V SM (VC)TCXO Clipped Sine						
Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass	
Base	Board	BT resin		19.000	18.05	
		Fibre glass	1309-37-1	38.000	36.11	
	Pattern	Cu	7440-50-8	38.000	36.11	
		Ni	7440-02-0	0.500	0.48	
		Au	7440-57-5	0.100	0.10	
	Resist ink	Resin		9.640	9.16	
Capacitor	Capacitor	Sn	7440.31-5	0.185	0.80	
		Ni	7440-02-0	0.185	0.80	
		Ag	7440-22-4	1.780	7.66	
		TiO2	13463-67-7	16.200	69.74	
		Pd	2023568	4.880	21.01	
Crystal unit	Ceramic	SiO2	14808-60-7	1.120	1.78	
		CaO	1305-78-8	0.110	0.17	
		MgO	1309-48-4	0.160	0.25	
		TiO2	13463-67-7	0.310	0.49	
		Cr2O3 (Non hex)	1308-38-9	1.200	1.91	
		Al2O3	1344-28-1	28.200	44.81	
	Crystal blank	SiO2	14808-60-7	1.508	2.40	
	Crystal Electrode	Au	7440-57-5	0.049	0.08	
		Cr	7440-47-3	0.001	0.00	
	Kovar	Fe	7439-89-6	4.320	6.86	
		Co	7440-48-4	1.539	2.45	
		Ni	7440-02-0	2.625	4.17	
	Metal layer	W	7440-33-7	6.210	9.87	
		Mo	7439-98-7	0.190	0.30	
	Nickel Plate	Ni	7440-02-0	0.800	1.27	
	Nickel plating	Ni	7440-02-0	0.427	0.68	
	Seal Ring	Fe	7439-89-6	6.200	9.85	
		Ni	7440-02-0	3.330	5.29	
	Silver solder	Co	7440-48-4	1.950	3.10	
		Ag	7440-22-4	1.450	2.30	
		Cu	7440-50-8	0.260	0.41	
	Gold Plate	Au	7440-57-5	0.280	0.44	
		Tl	7440-28-0	0.000	0.00	
	Nickel Plate	Co	7440-48-4	0.200	0.32	
	Adhesive	Ag	7440-22-4	0.370	0.59	
		Silicon Resin		0.125	0.20	
	Lid	German Silver	Ni	7440-02-0	42.000	19.05
			Cu	7440-50-8	126.000	57.14
			Zn	7440-66-6	52.500	23.81
	Resistor	Alumina board	Al2O3	1344-28-1	3.143	82.56
			SiO2	14808-60-7	0.097	2.55
		Plating	Ni	7440-02-0	0.086	2.26
Ni			7440-02-0	0.086	2.26	
Sn			7440.31-5	0.086	2.26	



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Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
	Protective glass	PbO	1317-36-8	0.033	0.87
		SiO2	14808-60-7	0.018	0.47
		B2O3	1303-86-2	0.007	0.18
		PbO	1317-36-8	0.033	0.87
		Al2O3	1344-28-1	0.002	0.05
	Resistance paste	PbO	1317-36-8	0.026	0.68
		SiO2	14808-60-7	0.014	0.37
		B2O3	1303-86-2	0.005	0.13
		Al2O3	1344-28-1	0.001	0.03
	Resistor paste	RuO2	12036-10-1	0.013	0.34
	Terminal paste	Ag	7440-22-4	0.047	1.23
		SiO2	14808-60-7	0.097	2.55
		Pd	2023568	0.004	0.11
		PbO	1317-36-8	0.005	0.13
		SiO2	14808-60-7	0.004	0.11
		B2O3	1303-86-2	0.000	0.00
		TiO2	13463-67-7	0.000	0.00

Solder cream					
	Solder cream	Sn	7440.31-5	19.300	96.50
		Ag	7440-22-4	0.600	3.00
		Cu	7440-50-8	0.100	0.50

Thermistor					
	Base Plating Electrode	Ni	7440-02-0	0.196	7.00
		Ag	7440-22-4	0.280	10.00
		Pd	2023568	0.030	1.07
	Element	Mn3O4	1317-35-7	0.640	22.86
		Co3O4	1308-06-1	1.010	36.07
	Finish Plating	Sn	7440.31-5	0.364	13.00
		Glass	PbO	1317-36-8	0.162
	SiO2		14808-60-7	0.096	3.43
	Cr2O3 (Non hex)		1308-38-9	0.016	0.57
	B2O3		1303-86-2	0.006	0.21

Transistor					
	Element	Si	7440-21-3	0.096	1.71
		Au	7440-57-5	0.010	0.18
	Frame	Fe	7439-89-6	1.100	19.65
		Ni	7440-02-0	0.782	13.97
		Cu	7440-50-8	0.252	4.50
		Other		0.022	0.39
		Others	Other		0.024
	Plating	Sn	7440.31-5	0.245	4.38
		Cu	7440-50-8	0.005	0.09
	Resin exterior	Si compound		2.130	38.04
		Sb2O3	1309-64-4	0.033	0.59
		Epoxy resin bromide	68541-56-0	0.106	1.89
		Organic phosphorus c		0.015	0.27
		Cr	7440-47-3	0.001	0.02
		Azo compound		0.015	0.27
		Other		0.742	13.25
		Wire	Au	7440-57-5	0.021

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Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Trimmer capacitor	Alloy	Other		1.793	20.38
		Other		1.966	22.34
	Plate	Ni	7440-02-0	0.005	0.06
		Si compound		0.018	0.20
	Ceramic	Al2O3	1344-28-1	4.787	54.40
	Plating	Ag	7440-22-4	0.201	2.28
		Ni	7440-02-0	0.013	0.15
		Sn	7440.31-5	0.017	0.19
Total Mass:				452.910 mg	



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